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60,000

21,000,000

4,654,520	8,078,511
8,901,705	4,346,501
6,805,210	6,688,570



STAR LAKE

EN50155 RAILWAY 1U FANLESS SERVER



- Adheres EN50155 TX Railway 1U Server
- Design for reliability under MIL-810 Thermal, Shock, Vibration, Humidity EMI/EMC conditions
- Intel Coffee-Lake 9th Gen. i7-9700TE Processor
- Anti-corrosion stainless steel with M12 connector
- Dual 2.5" SSD/HDD Hot swappable Tray
- DC-DC 34V to 62V
- Extended Temperature -40 to 70 °C

Specifications

SYSTEM

CPU	8 th /9 th Gen Intel® Coffee Lake-R LGA1151 Socket Processor Intel® Core i7-9700TE (8 core / 8 Threads , 12M Cache , up to 3.8 GHz , 35W)
Memory type	2 x SO-DIMM DDR4 2666 MHz up to 64GB
Chipset	Intel® Q370 Chipset
Expansion Slot	PCIe 3.0 X16 slot M.2 2230 E key (PCIe, USB 2.0) M.2 2242 / 2280 M key (PCIeX4, SATA) Mini PCIe Full size (PCIe / USB / SATA)

DISPLAY

eDP(option)	Up to 4K (4096 x 2304) @60 Hz
HDMI	Up to 4K (4096 x 2160) @30 Hz
DP	Up to 4K (4096 x 2304) @60 Hz

ETHERNET

Ethernet 1(RJ45)	Intel® I219-LM Giga LAN + Intel® I210-AT Giga LAN
Ethernet 2(M12)	MiniPCIe to LAN or M.2 2242 to LAN

REAR I/O

DP	2
HDMI	1
USB	4 x USB3.1 (standard-A connectors)
Audio	1 x LINE-IN ; 1 x MIC-OUT(3.5mm Audio Jacks)
Ethernet 1	2 x RJ45
Ethernet 2	2 x M12 X-Code Male connector (Phoenix 8 PIN , Housing: 1414020, Internal Bladder:1413446)
DC-IN	1 x M12 X-code Male connector (Amphenol 4-Pin Connector (M12S-04PMMS-SF8001)
Power Button	1

FRONT I/O

SSD Tray	2
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POWER REQUIREMENT

DC-IN	DC-IN 34V~62V (24V/72V/110V for Options)
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OPERATING SYSTEM

Operating System	Microsoft Windows 10 Professional 32/64Bit, Ubuntu18.04, Fedora 20.
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PHYSICAL

Dimension (W x D x H)	440 x 360 x 44 mm
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Weight	9.05 Kg (19.95 lbs)
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Chassis	Stainless Steel , Corrosion Resistant
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Cooling	Natural Passive Convection/Conduction. No Moving Parts.
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ENVIRONMENTAL

MIL-STD-810G Test	Method 507.5, Procedure II (Temperature & Humidity) Method 514.6, Procedure I (Category 20 & 24, Vibration) Method 516.6, Procedure I (Mechanical Shock) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock)
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EN50155 Compliance Test	Clause 12.2.1 Visual inspection Clause 12.2.2 Performance test Clause 12.2.9 Insulation test Clause 12.2.11 Vibration, shock and bump test
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Reliability	No Moving Parts; Passive Cooling. Designed & Manufactured using ISO 9001/2000 Certified Quality Program.
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EMC	CE and FCC compliance
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Green Product	RoHS, WEEE compliance
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Ordering Information

EN286A-ET

1U Rackmount Fanless System with 8th/9th Gen. Intel® Core™ i, 1 x AUDIO , 4 x USB3.1 , 2 x DP , 1 x HDMI , 4 x LAN(include 2 x M12) , 33V~64V DC-IN(M12), Extended Temp. -20~60°C

EN286A-UT

1U Rackmount Fanless System with 8th/9th Gen. Intel® Core™ i, 1 x AUDIO , 4 x USB3.1 , 2 x DP , 1 x HDMI , 4 x LAN(include 2 x M12) , 33V~64V DC-IN(M12), Extended Temp. -40~70°C

Drawings

